

Product Description

The raw material for WillowFlex FX1504 is a unique elastomeric bioplastic with a diverse range of potential applications. The bioplastic is verified to meet U.S. (ASTM D6400) and E.U. (EN 13432) standards for compostability.

Applications

This material is suitable for injection molding, profile extrusion, sheet extrusion, blow molding, and blown film.

Processing Recommendations:

Drying: Resin must be dried before processing.

Drying Conditions: Out of a sealed box – 32° - 38°C (90° to 100° F) for 2 to 3 hours

Open Box – 38° - 50°C (100° to 120° F) for 4 to 5 hours

Suggested Temperature Settings:

Extruder Zone	Rear	Center	Front	Nozzle
Temperature °C	150°- 165°	150°- 165°	150°- 165°	150°- 165°
Temperature °F	300°- 329°	300° - 329°	300° - 329°	300° - 329°

Processing at temperatures above 175° C and in combination with high shear conditions such as high injection speed may result in thermal degradation of this resin.

FX1504 resin is typically packaged in a sealed plastic-lined fiber drum of 250 lbs (112 kg). The product should be stored in a cool, dry, and sanitary area to achieve maximum stability.

Custom Formulations:

Specific recommendation for processing WillowFlex FX1504 can be made based on customer equipment and processes. Contact us directly for details, requirements and limitations.

Physical Properties	Test Method	Value	Unit
Specific Gravity	ASTM D792	1.23	g/cm ³
Izod Impact	ASTM D256	6.06	ft lb/in
Tensile Strength	ASTM D638	1,873	psi
Tensile Modulus	ASTM D638	16,097	psi
Flex Strength	ASTM D790	762	psi
Flex Modulus	ASTM D790	16,097	psi
Melt Index (190°C & 2160g)	ASTM D1238	41.9	g/10min
Shrinkage (190°C & 2160g)	ASTM D1238	.0095	In/in

The information and recommendations in this sheet are based on our experience and analysis using standard procedures, and are believed to be accurate and reliable. However, they serve merely as typical guides, and are presented in good faith for the benefit of our customers. No guarantee, expressed or implied, is made regarding accuracy of the analysis, patent infringement, liabilities, or risks involved from the application of our products.